

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant: Joseph E. Geusic et al.

Title: INTEGRATED CIRCUITS USING OPTICAL FIBER INTERCONNECTS FORMED  
THROUGH A SEMICONDUCTOR WAFER

Docket No.: 303.390US4

Serial No.: 10/772,606

Filed: February 5, 2004

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Examiner: Julio J Maldonado

Group Art Unit: 2823

Customer No.: 21186

Confirmation No.: 5065

Commissioner for Patents

**Notice of Allowance Date:**

Attn: MAIL STOP ISSUE FEE

July 28, 2005

P.O. Box 1450

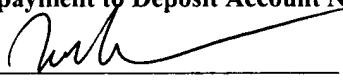
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SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.

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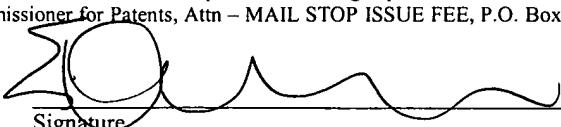
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**CERTIFICATE UNDER 37 CFR 1.8:** The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: Commissioner for Patents, Attn – MAIL STOP ISSUE FEE, P.O. Box 1450, Alexandria, VA 22313-1450, on this 28 day of October, 2005.

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